

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(multi adj chip with package and semiconductor and device and comprising and insulating adj substrate and first adj conductive adj pattern and second adj conductive adj pattern and first adj semiconductor adj chip and plurality adj first adj internal adj circuits and plurality adj first adj terminal adj pads and plurality adj conductive adj relay adj pads and alternatively adj aligned and smaller and first adj metal adj bumps).clm.	US-PGPUB	OR	ON	2006/05/11 19:25